SML-P1 series PICOLED[™]

Features

ROHM

- Ultra compact, thin size 1.0×0.6mm
- · Original device technology enables high brightness and high reliability
- Lead Free/RoHS Compliant.

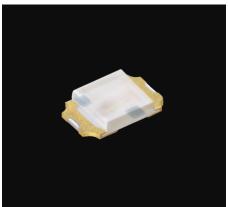
Size

Dimensions

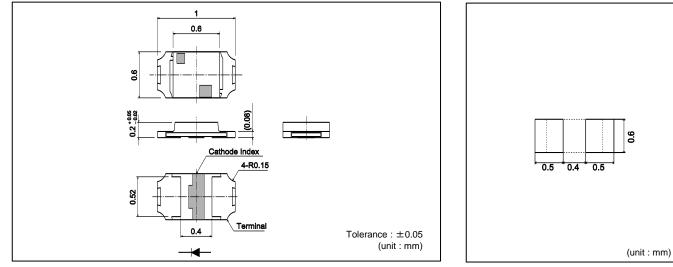
1006 (0402)	
1.0×0.6mm (t=0.2mm)	

Color Type	V	U	D	Y
М	Ρ	E	В	WB

Outline



Recommended Solder Pattern



Specifications

				Abs	solute Max	kimum Ra	atings (Ta=25°C	C)			Electri	cal and	I Optica	I Chara	acteristi	ics (Ta	=25°C)				
Part No.	Chip	Emitting	Power	Forward	Peak Forward	Reverse	Operating Tomp	Storage Temp.	Forward	Voltag V _F	Reverse	Current I _R	Domir	nant Wa	aveleng	ith λD	Lumino	ous Inte	nsity I _v		
Tarrio.	Structure	Color	Dissipation	Current	Current	Voltage	operating remp.	otorage remp.	Тур.	I _F	Max.	V _R	Min.*2	Тур.	Max.*2	١ _F	Min.	Тур.	I _F		
			$P_D(mW)$	I _F (mA)	I _{FP} (mA)	$V_{R}(V)$	Topr(⁰C)	Tstg(ºC)	(V)	(mA)	(μA)	(V)	(nm)	(nm)	(nm)	(mA)	(mcd)	(mcd)	(mA)		
SML-P12VT(R)		Red	50						2.0				625	630	635		25	60			
SML-P12UT(R)		Reu	50	50	50						2.0				615	620	625		40	85	
SML-P12DT(R)	AlGalnP	Orange	52	20	100* ¹				2.1	20		4	602	605	608	20	63	100	20		
SML-P12YT(R)	on GaAs			20	100				2.1	20		4	587	590	593	20	40	100	20		
SML-P12MT(R)		Yellowish Green	54				5	-40 to +85	-40 to +100	2.2	100	100	569	572	575		10	25			
SML-P12PT(R)		Green							2.2				557	560	563		2.5	6.3			
SMLP13EC8T		Bluish Green	34						3.0				520	527	535		56	(110)			
SMLP13BC8T	InGaN	Blue	33	10	50* ¹				2.9	5		5	465	470	475	5	9.0	(25)	5		
SCMP13WBC8W		White							2.9				(x, y)	(0.30,	0.30)		90	150			

*1 : Duty 1/10, 1kHz *2 : Reference

Thermal Resistance

θj-s 643°C/W

Өј-а	Conditions	Circuit Board	Glass epoxy circuit board
899°C/W		Circuit Board Dimensions	30×10×0.8mmt
		Pad Size	1.5mm ² (Cathode)

*The above value is a result of actual measurement performed

on randomly selected product. The value does not have any meanings of guarantee.

*PICOLED[™] is ROHM's pending trademark.

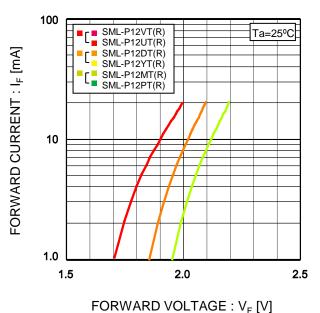


Fig.1 Forward Current - Forward Voltages

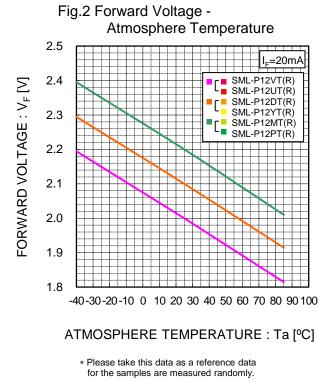


Fig.3 Luminous Intensity -Fig.4 Luminous Intensity - Forward Current Atmosphere Temperature 1.6 1.2 RELATIVE LUMINOUS INTENSITY [a.u.] I_F=20mA SML-P12VT(R) SML-P12UT(R) <u>ר</u> Ta=25⁰C RELATIVE LUMINOUS INTENSITY SML-P12DT(R) 1.4 1.0 SML-P12YT(R) SML-P12MT(R) SML-P12PT(R) 1.2 0.8 1.0 0.6 0.8 0.4 SML-P12VT(R) SML-P12UT(R) SML-P12DT(R) 0.6 0.2 SML-P12YT(R) SML-P12MT(R) SML-P12PT(R) 0.4 0.1 -40 -20 0 20 40 60 80 100 5 10 15 20 0 ATMOSPHERE TEMPERATURE : Ta [°C] FORWARD CURRENT : I_F [mA]

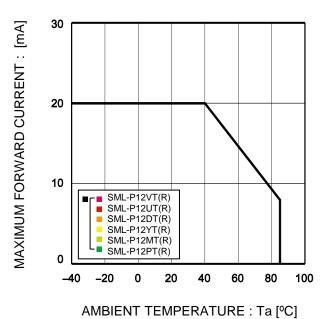


Fig.5 Derating



Data Sheet

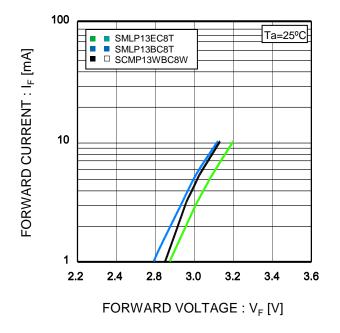
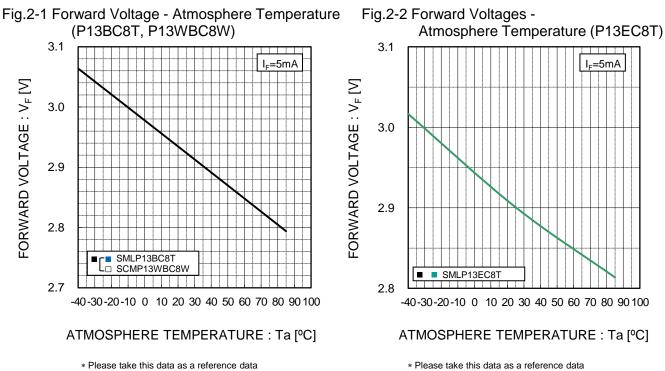
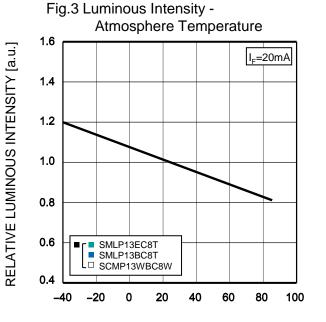


Fig.1 Forward Current - Forward Voltages



* Please take this data as a reference data for the samples are measured randomly.

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ATMOSPHERE TEMPERATURE : Ta [°C]

Fig.5 Derating

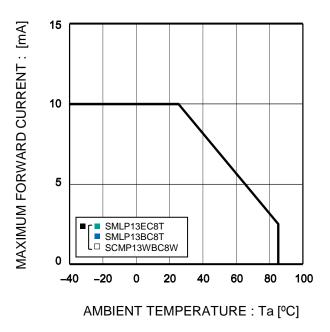
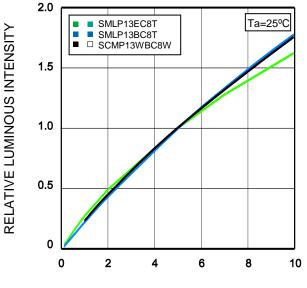
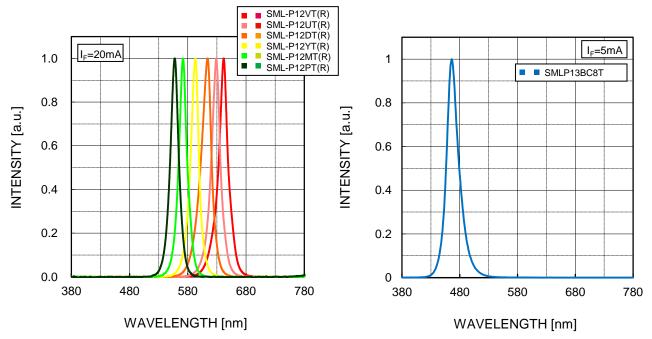


Fig.4 Luminous Intensity - Forward Current



FORWARD CURRENT : I_F [mA]

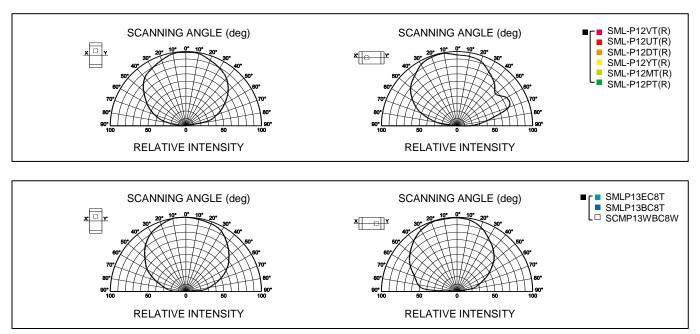
•Spectrum Data



* Please take this data as a reference data for the samples are measured randomly.

* The data is relativized for each color. It is NOT to show the spectrum peaks are equal.

•Viewing Angle

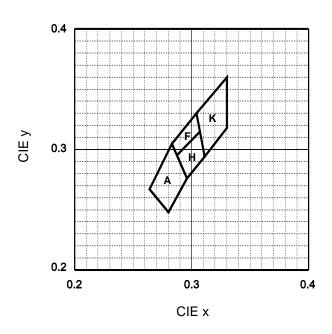


•Rank Reference of Brightness

Red(V,U)														(Ta=25⁰C,	I _F =20mA)
Rank	G	Н	J	K	L	М	N	Р	Q	R	S	Т	U	V	W	Х
lv (mcd)	1.0 to 1.6	1.6 to 2.5	2.5 to 4.0	4.0 to 6.3	6.3 to 10	10 to 16	16 to 25	25 to 40	40 to 63	63 to 100	100 to 160	160 to 250	250 to 400	400 to 630	630 to 1000	1000 to 1600
SML-P12VT																
SML-P12UT																
Orange(,														(Ta=25⁰C,	I _F =20mA)
Rank	G	Н	J	K	L	М	N	Р	Q	R	S	Т	U	V	W	Х
lv (mcd)	1.0 to 1.6	1.6 to 2.5	2.5 to 4.0	4.0 to 6.3	6.3 to 10	10 to 16	16 to 25	25 to 40	40 to 63	63 to 100	100 to 160	160 to 250	250 to 400	400 to 630	630 to 1000	1000 to 1600
SML-P12DT																
Yellow(Y	,													-	(Ta=25ºC,	, ,
Rank	G	Н	J	K	L	M	N	Р	Q	R	S	Т	U	V	W	Х
Iv (mcd)	1.0 to 1.6	1.6 to 2.5	2.5 to 4.0	4.0 to 6.3	6.3 to 10	10 to 16	16 to 25	25 to 40	40 to 63	63 to 100	100 to 160	160 to 250	250 to 400	400 to 630	630 to 1000	1000 to 1600
SML-P12YT																
Green(N Rank Iv (mcd)	I,P) G 1.0 to 1.6	H 1.6 to 2.5	J 2.5 to 4.0	K 4.0 to 6.3	L 6.3 to 10	M 10 to 16	N 16 to 25	P 25 to 40	Q 40 to 63	R 63 to 100	S 100 to 160	T 160 to 250	U 250 to 400	V	(Ta=25°C, W 630 to 1000	Х
SML-P12MT	1															
SML-P12PT																
Bluish G		,	-	-	-	-	-	-	-	-	_		-		, I _F =5mA)	
Rank	G	Н	J	К	L	M	N	Р	Q	R	S	Т	U	V	W	
Iv (mcd)	0.9 to 1.4	1.4 to 2.2	2.2 to 3.6	3.6 to 5.6	5.6 to 9.0	9 to 14	14 to 22	22 to 36	36 to 56	56 to 90	90 to 140	140 to 220	220 to 360	360 to 560	560 to 900	
SMLP13EC8T																
Blue(B)														(Ta=25⁰C	;, I _F =5mA)	-
Rank	G	Н	J	K	L	М	N	Р	Q	R	S	Т	U	V	W	
lv (mcd)	0.9 to 1.4	1.4 to 2.2	2.2 to 3.6	3.6 to 5.6	5.6 to 9.0	9 to 14	14 to 22	22 to 36	36 to 56	56 to 90	90 to 140	140 to 220	220 to 360	360 to 560	560 to 900	
SMLP13BC8T																
White(W	/B)							(Ta=25⁰C	, I _F =5mA)							
Deel		-	<u> </u>		0	-			14/	1						

vvnite(vv	в)							(Ta=25⁰C	, I _F =5mA)
Rank	Ν	Р	Q	R	S	Т	U	V	W
lv (mcd)	14 to 22	22 to 36	36 to 56	56 to 90	90 to 140	140 to 220	220 to 360	360 to 560	560 to 900
SCMP13WBC8W									

Chromaticity Diagram

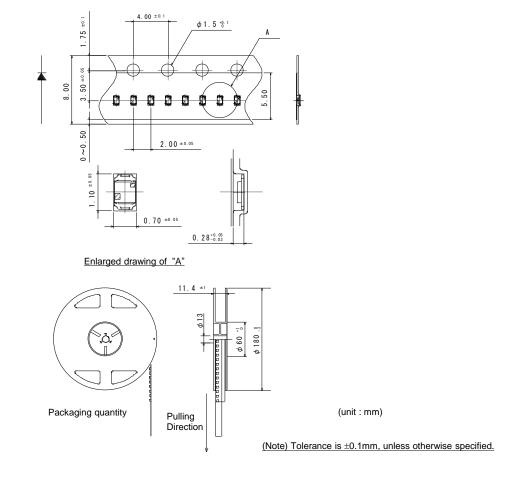


[Chromaticity Coordimates]

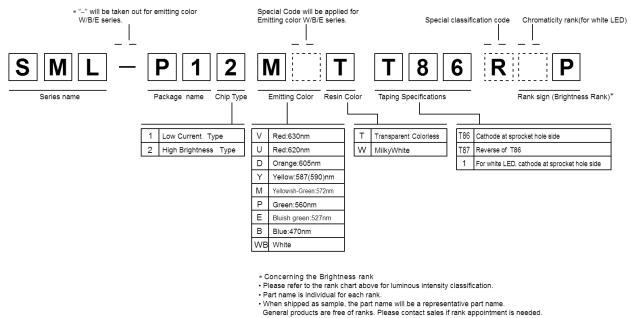
					(Ta=2	5ºC, I _F =	=5mA)	
ŀ	4		F	ł	ł	K		
х	у	х	у	х	у	х	у	
0.28	0.248	0.283	0.305	0.287	0.295	0.304	0.33	
0.296	0.276	0.304	0.33	0.307	0.315	0.33	0.36	
0.283	0.305	0.307	0.315	0.311	0.294	0.33	0.318	
0.264	0.267	0.287	0.295	0.296	0.276	0.311	0.294	

Measurement tolerance ± 0.02

Taping



•Part No. Construction



Packing Specification

ROHM LED products are being shipped with desiccant (silica gel) concluded in moisture-proof bags.

Pasting the moisture sensitive label on the outer surface of the moisture-proof bags or enclosing the humidity indication card

inside the bag is available upon request.

Please contact the nearest sales office or distributer if necessary.

•Attention Points In Handling

This product was developed as a surface mount LED especially suitable for reflow soldering. Please take care of following points when using this device.

1.DESIGNING OF PCB

As for a recommendable solder pattern, Please refer to Fig "Recommended Solder Pattern".

The size and direction of the pad pattern depend on the condition of the PCB.

This product of structured with rear/bottom electrode to be soldered.

The formation of solder fillet is not guaranteed due to its electrode shape

Additional notification of mounting :

We recommend additional facility of mounting Machine due to small size package

which might be haven electrification, and product might be moved in the taping pocket.

And the mounting production efficiency will be decreased.

Ex) Magnet facility etc.

2.SOLDERING (Sn-Cu, Sn-Ag-Cu, Sn-Ag-Bi-Cu)

LED products do not contain reinforcement materials such as glass fillers.

Therefore, thermal stress by soldering greatly influences its reliability.

The temperature conditions for reflow soldering should therefore be set up according to the characteristic of this product. (See Fig-1) Number of reflow process shall be max 2 times and these processes shall be performed in a row. Cooling process to normal temperature shall be required between the first and the second soldering process.

SOLDERING OPERATION

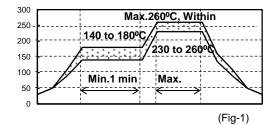
1) SOLDER USED

Sn-Cu, Sn-Ag-Cu, Sn-Ag-Bi-Cu

2) SOLDERING CONDITION

LED products do not contain reinforcement material such as a glass fillers. So thermal stress by soldering greatly influence its reliability.

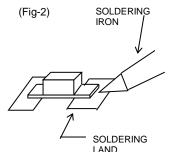
Please keep following points for manual soldering.



Reference

Mask open area ratio : 80%

Mask thickness : 80 to 100µm



	ITEM	RECOMMENDED CONDITION
a)	Soldering iron	Less than 30W, top of iron less than 3mm.
		Condition) Temp. of iron top less than
b)	Heating method	400°C within 3 sec.
		Heating on PCB pattern, not direct to the LED. (Fig-2)
	Handling after soldering	Please handle after the part temp.
c)	rianuling after soluering	Goes down to room temp.

3.HANDLING AFTER MOUNTING (Fig.-3)

As shown in the drawing on the right, in case outside force of about 700g is given to the device, stress is concentrated to the jointed part between mold resin and substrate.

Therefore there is a possibility to breath the device or PCB.

Careful handing is needed as ROHM cannot guarantee the falling of the device by outside force after mounting.

4.WASHING

Please note the following points when washing is required after soldering.

4-1) WASHING SOLVENT

Isopropyl alcohol or other alcohol solvent is recommendable.

4-2) TEMPERATURE

Below 30°C, immersion time ; within 3 minutes.

4-3) ULTRA SONIC WASHING

Below 15W/1 litter of solvent tub or less.

4-4) COOLING

Below 100°C within 3 minutes.

5.EROSION GAS

Utilization in erosion gas atmosphere may degenerate the plating surface which might cause deterioration of solder strength, optical characteristics, or functions.

Please take precautions against occurrence of gas from the surrounding parts on the occasion of custody, and also after mounted on circuit board.

6.STORAGE

At reflow soldering, the reliability of this product is often influenced by moisture absorption so we apply the packaging with moisture proof for better condition is use, please also note that 6-1) Not to be opened before using

- 6-1) Not to be opened before using.
- 6-2) To be kept in our moisture proof packaging with some desiccant (SILICA GEL) after opening it.To be baked in case the SILICA GEL indicator its color from either blue to clear or green to pink.
- 6-3) Please use within 168 hours after the package was opened. (Condition at 30°C, max.70%Rh.)In case it is not used within 168 hours, please put it back into our packaging.
- 6-4) BAKING

Please bake under reel condition at 60°C, 1 to 224 hours (max.20%Rh) after un-sealing. While baking is done, the reel and emboss tape may be easily deformed. Please be careful not to give any stress.

7.LIFE TIME

Blue led die used in this product will cause reduction of luminous intensity due to epoxy resin discoloration depending on the using conditions and environmental.

Please inquire our sales contact if long life time is required on your application.

	Notes
1)	The information contained herein is subject to change without notice.
2)	Before you use our Products, please contact our sales representative and verify the latest specifications :
3)	Although ROHM is continuously working to improve product reliability and quality, semicon- ductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM.
4)	Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The periphera conditions must be taken into account when designing circuits for mass production.
5)	The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly any license to use or exercise intellectual property or other rights held by ROHM or any othe parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use o such technical information.
6)	The Products are intended for use in general electronic equipment (i.e. AV/OA devices, communi cation, consumer systems, gaming/entertainment sets) as well as the applications indicated in this document.
7)	The Products specified in this document are not designed to be radiation tolerant.
8)	For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.
9)	Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.
10)	ROHM shall have no responsibility for any damages or injury arising from non-compliance with the recommended usage conditions and specifications contained herein.
11)	ROHM has used reasonable care to ensur the accuracy of the information contained in this document. However, ROHM does not warrants that such information is error-free, and ROHM shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.
12)	Please use the Products in accordance with any applicable environmental laws and regulations such as the RoHS Directive. For more details, including RoHS compatibility, please contact a ROHM sales office. ROHM shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.
13)	When providing our Products and technologies contained in this document to other countries you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act.
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